



Introduction

The SPC564Bxx and SPC56ECxx is a family of Power Architecture[®] based microcontrollers that target automotive vehicle body and gateway applications such as Central body controller, Smart junction boxes, Front modules, High end gateway, Combined Body controller and gateway.

These dual core architecture devices contain an e200z4d and e200z0h core, compliant with the Power Architecture standard.

It provides the scalability needed to implement platform approaches and delivers the performance required by increasingly sophisticated software architectures.

These devices feature up to 3 MB of internal Flash and up to 256 KB of internal SRAM memory.

It operates at speeds of up to 120 MHz and offers high performance processing optimized for low power consumption.

The SPC564Bxx and SPC56ECxx family expands the range of the SPC560B/C microcontroller family but differs from it by being the first device to feature the e200z4d core and the e200z0h in a dual core configuration.

The differences between this family and the previous one (SPC560B/C) mean that the initialization and configuration are different.

This application note details the steps required to properly initialize the SPC564Bxx and SPC56ECxx from reset as well as how to control the second core. An example code is described throughout the application note to explain the steps.

It is intended that this application note is read along with the *SPC564Bxx and SPC56ECxx Reference Manual*, RM0070 that can be obtained from the STMicroelectronics[®] website at <http://www.st.com> (see [Section C.1: Reference document](#)).

Contents

1	Application example description	6
2	Microcontroller boot	7
2.1	Boot mechanism	7
2.1.1	Bootable sectors and RCHW	8
3	e200z4d initialization and example code	10
3.1	Creating e200z4d Flash boot file	10
3.1.1	MMU remarks	10
3.1.2	Configure MMU for SRAM	13
3.1.3	Initialize the SRAM ECC	14
3.1.4	Configure MMU for Flash	14
3.1.5	Configure MMU for Peripheral Bridge	16
3.1.6	Memory initialization	16
3.1.7	Performance Hints Initialization	19
3.2	e200z4d device configuration from C code	24
3.2.1	Disable watchdog	24
3.2.2	Mode configuration and clocking	25
3.2.3	Clock & PLL configuration	28
3.2.4	Configure Cache	29
3.2.5	Starting the e200z0h core	30
3.3	The e200z4d example code	31
4	e200z0h Initializations and example code	32
4.1	e200z0h startup code	32
Appendix A	Application code example	34
A.1	main.c file	34
A.2	crt0_corez4_Flash.s	38
Appendix B	Linker file	44
Appendix C	Further information	47
C.1	Reference document	47

C.2 Acronyms and abbreviations..... 47

Revision history 48

List of tables

Table 1.	Boot mode selection	7
Table 2.	RCHW field description	9
Table 3.	Example of MMU configuration	12
Table 4.	Memory partition schema	44
Table 5.	Acronyms and abbreviations	47
Table 6.	Document revision history	48

List of figures

Figure 1.	Boot sector structure.	9
Figure 2.	SPC564Bxx/SPC56ECxx block diagram	11
Figure 3.	MMU configuration code for SRAM	13
Figure 4.	SRAM ECC initialization code	14
Figure 5.	MMU configuration code for Flash	15
Figure 6.	Code to copy configuration code from Flash to SRAM.	15
Figure 7.	MMU configuration code for peripherals area.	16
Figure 8.	Boot flow using GHS startup libraries	17
Figure 9.	Startup file: __ghs_board_memory_init	18
Figure 10.	Startup file: branch to GHS startup libraries	18
Figure 11.	Startup file: enable BTB and SPE.	19
Figure 12.	Startup file: Flash Configuration code.	20
Figure 13.	Startup file: SRAM wait states configuration code	20
Figure 14.	Startup file: XBAR register configuration values.	21
Figure 15.	Startup file: XBAR configuration code	22
Figure 16.	Cache Configuration Code	23
Figure 17.	Environment configurations code	24
Figure 18.	SWT disabling code	25
Figure 19.	Mode entry diagram	26
Figure 20.	Mode Initialization Code	26
Figure 21.	Peripheral Control Registers.	27
Figure 22.	Run peripheral control registers	27
Figure 23.	System clock dividers configuration code.	28
Figure 24.	PLL configuration code.	29
Figure 25.	Application code: the main function	31
Figure 26.	e200z0h startup code	33

1 Application example description

This application note describes the necessary steps to configure the device in order to run two independent codes on the two cores.

This family is quite different from the previous one, indeed apart from the memories size now it has been introduced the dual core concept: in the SPC564Bxx and SPC56ECxx family the primary core is an e200z4d while the second one is a e200z0h.

While the second core (e200z0h) is thought only as performance core (only to speed up the execution), the introduction of the e200z4d implies that the user has a more powerful architecture to cope with the application tasks.

The availability of MMU, ICache and Signal Processing instructions enhance the performance, but require the correct configuration.

The example code described herein toggles two LEDs with each core running the application independent of the other.

It has been chosen to treat the two applications separately to better understand the dual core concept even for compiler projects: of course each project produces one executable image. The user then has to program the device with both executable images (the instruction codes are located in different places).

Following this strategy the device is perceived as two separate MCUs each with proprietary Flash and SRAM.

In this application note, it has been decided to split (in equal parts) the Flash and the SRAM for both cores.

The memory partition and the XBAR (crossbar architecture) have been optimized for dual core operations and in particular to give priority to e200z4d core (see [Section 3.1.7: Performance Hints Initialization](#)):

- The SRAM is split over 2 slave ports, 0x4000_0000 to 0x4001_FFFF on slave port 2 (used by e200z4d) and 0x4002_0000 to 0x4003_FFFF on slave port 3 (used by e200z0h);
- There are 2 Flash ports, z4 instruction port on slave port 0 and a second Flash port for everything else on slave port 1.

By splitting the SRAM in the linker file(s) so that the e200z4d has access to one block and the e200z0h has access to the other block, crossbar contentions are generally avoided between the cores for SRAM access^(a) (see [Appendix B: Linker file](#)).

a. When, for example, there are large amounts of DMA transfers to/from SRAM it could be useful to use the SRAM allocated to the processor which allows fewer accesses to SRAM. User has to take care that none of this prevents either core from writing the full SRAM array so care has to be taken in software (using semaphores and / or software interrupts) to ensure memory coherency.

2 Microcontroller boot

This chapter describes the configuration required by the user, and the steps performed by the microcontroller^(b) and in particular, by the SSCM (System Status and Configuration Module), in order to achieve a successful boot from Flash memory.

For further information, look at SPC564Bxx and SPC56ECxx Reference Manual (see [Section C.1: Reference document](#)).

2.1 Boot mechanism

SPC564Bxx and SPC56ECxx family (as other SPC56xx devices), has two hardware boot configuration pins, FAB (Force Alternate Boot mode) and ABS (Alternate Boot Select). These 2 external pins on the microcontroller are latched during reset and used by the SSCM to determine whether the microcontroller boots from Flash memory or attempts a serial download via FlexCAN or LINFlex (RS232) (see [Table 1](#)).

In this application note, the focus is on the default operating mode: the Flash boot mode.

Table 1. Boot mode selection

Mode	FAB pin (PA[9])	ABS pin (PA[8])
Flash Boot (Default Mode)	0	–
Serial Boot (LINFlex)	1	0
Serial Boot (FlexCAN)	1	1

When the device is powered on, the SSCM (System Status Configuration Module) searches the pre-determined locations in Flash for a valid RCHW (Reset Configuration Half Word) (see [Section 2.1.1: Bootable sectors and RCHW](#)).

- If a valid BOOT_ID is found, the SSCM reads the VLE bit and the boot vector address (as well as the CSE block size).
- If a valid BOOT_ID is not found, the SSCM starts the process of putting the microcontroller (e200z4d) into static mode^(c). See SPC564Bxx and SPC56ECxx family Reference Manual for detailed information (see [Section C.1: Reference document](#)).

Note: The static mode differs from safe mode. Static mode is a non-operational mode which can only be entered via the BAM (Boot Assist Module).

b. The booting mechanism has an impact only on the e200z4d core.

c. Static Mode Sequence:

1. The SSCM creates a 4 KB MMU page at the start of the BAM with the VLE bit set (the BAM is VLE code).
2. The SSCM then sets the CPU core (e200z4d) instruction pointer to the BAM address and the core starts to execute the code to enter static mode as follows:
 - the Software Watchdog Timer (SWT) is enabled;
 - the core executes the "wait" instruction which halts the core.

After the microcontroller enters static mode, the SWT periodically resets the core (approximately every 10 ms) to re-attempt a boot from Flash memory.

In all these conditions, the e200z0h core remains held in reset: for further information please refer to *SPC564Bxx and SPC56ECxx Reference Manual*, RM0070 (see [Section C.1: Reference document](#)).

In order to access memory (for the e200z4d core), a valid MMU TLB entry has to be created. The SSCM does this automatically by reading the reset vector and modifying TLB entry 0 to create a 4 KB page containing the reset vector address.

The MMU VLE bit is set depending on the status of the VLE bit within the RCHW. The 4 KB MMU page^(d) must be 4 KB aligned. This means that the most efficient place to put the application code is immediately after the boot sector (see [Section 2.1.1: Bootable sectors and RCHW](#)). So in order to maximize the available space inside the 4 KB block, the reset vector should be set close to the start of a 4 KB boundary.

Note: For example, if the reset vector is set to address 0x0000_0020, then the SSCM aligns the 4 KB MMU page to the start of the 4 KB aligned block containing address 0x0000_0020 – an MMU page starting at address 0x0000_0000.

Similarly, if the reset vector is set to address 0x0000_0FF0 which is towards the end of an aligned 4 KB block, the MMU page still has to start at 0x0000_0000 leaving very little room in the 4 KB MMU page for code execution.

Finally, the SSCM sets the e200z4d core instruction pointer to the reset vector address and starts the core running.

2.1.1 Bootable sectors and RCHW

In order to successfully boot from Flash memory, the user must program two 32-bit fields into one of the 5 possible boot blocks (see [Figure 1](#)).

The entities to program are:

- 16-bit Reset Configuration Half Word (RCHW), which contains:
 - A BOOT_ID field that must be correctly set to 0x5A in order to "validate" the boot sector;
 - A VLE bit which configures the initial MMU entry to either Power Architecture Book VLE or Power Architecture Book III-E as described later on in this chapter;
- 32-bit reset vector (this is the start address of the user code)

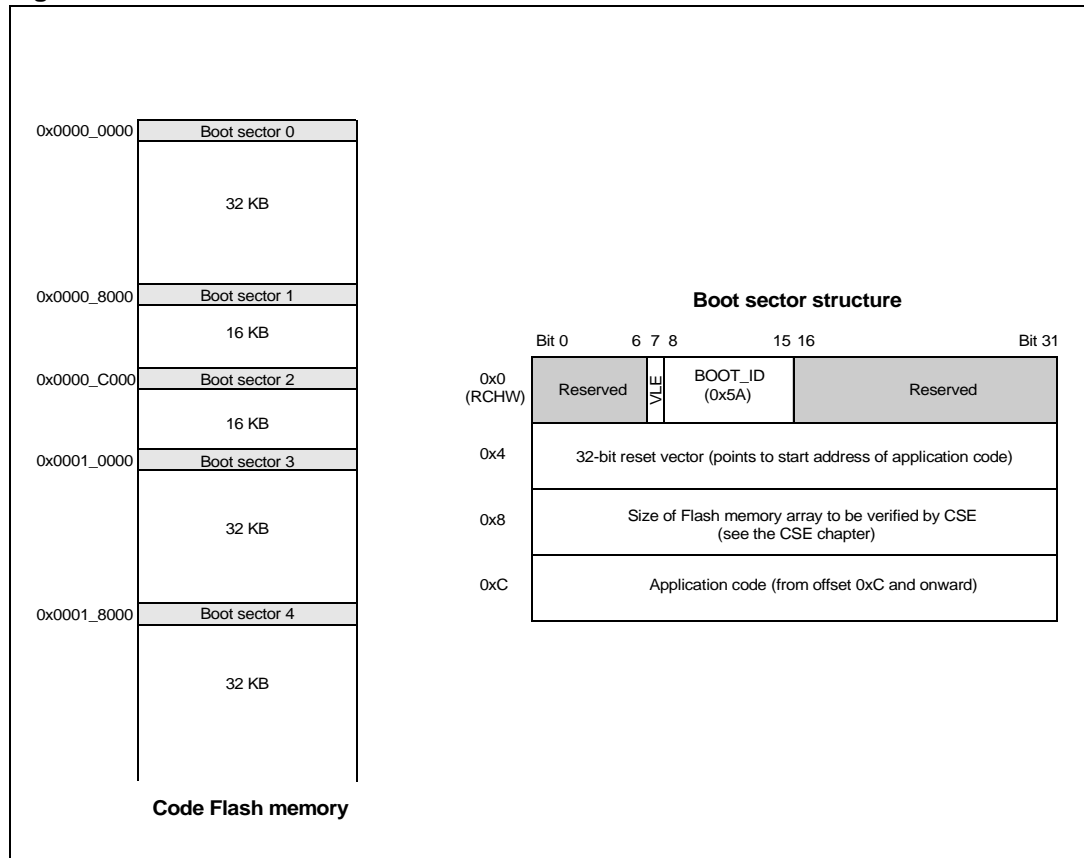
The boot sector also contains a 32-bit field containing the size of the block of data to be checked by the CSE (Cryptographic Security Engine) during a secure boot. See *SPC564Bxx and SPC56ECxx family Reference Manual*, RM0070 for detailed information ([Section C.1: Reference document](#)).

Note: Application code can then be programmed from offset address 0x000C.

d. The 4 KB block provides sufficient space to the user to:

1. Add MMU entries for SRAM and peripherals
2. Perform standard system initialization tasks (initialize the SRAM, setup stack, copy constant data)
3. Transfer execution to RAM, re-define the Flash memory MMU entry and transfer execution back to Flash memory.

Figure 1. Boot sector structure



The structure of RCHW is described in [Table 2](#):

Table 2. RCHW field description

Field	Description
VLE	VLE Bit 0 MMU TLB Entry 0 is configured for Power Architecture Book III-E. 1 MMU TLB Entry 0 is configured for Power Architecture Book VLE.
BOOT_ID	Boot identifier. If BOOT_ID = 0x5A, the boot sector is considered valid and bootable.

3 e200z4d initialization and example code

3.1 Creating e200z4d Flash boot file

In order to run an application from Flash memory, the user code must perform a series of mandatory actions for proper execution:

- Provide reset vector in the location after the RCHW ([Section 2.1: Boot mechanism](#));
- Configure MMU;
- Initialize SRAM (ECC) (see [Section 3.1.3: Initialize the SRAM ECC](#));
- Configure wait states for Flash and SRAM (see [Section 3.1.7: Performance Hints Initialization](#));
- Configure XBAR (see [Section 3.1.7: Performance Hints Initialization](#));
- Enable SPE (Signal Processing Extension) instructions if needed by the application
- Enable BTB^(e) (Branch Prediction Buffers) (see [Section 3.1.7: Performance Hints Initialization](#)).

3.1.1 MMU remarks

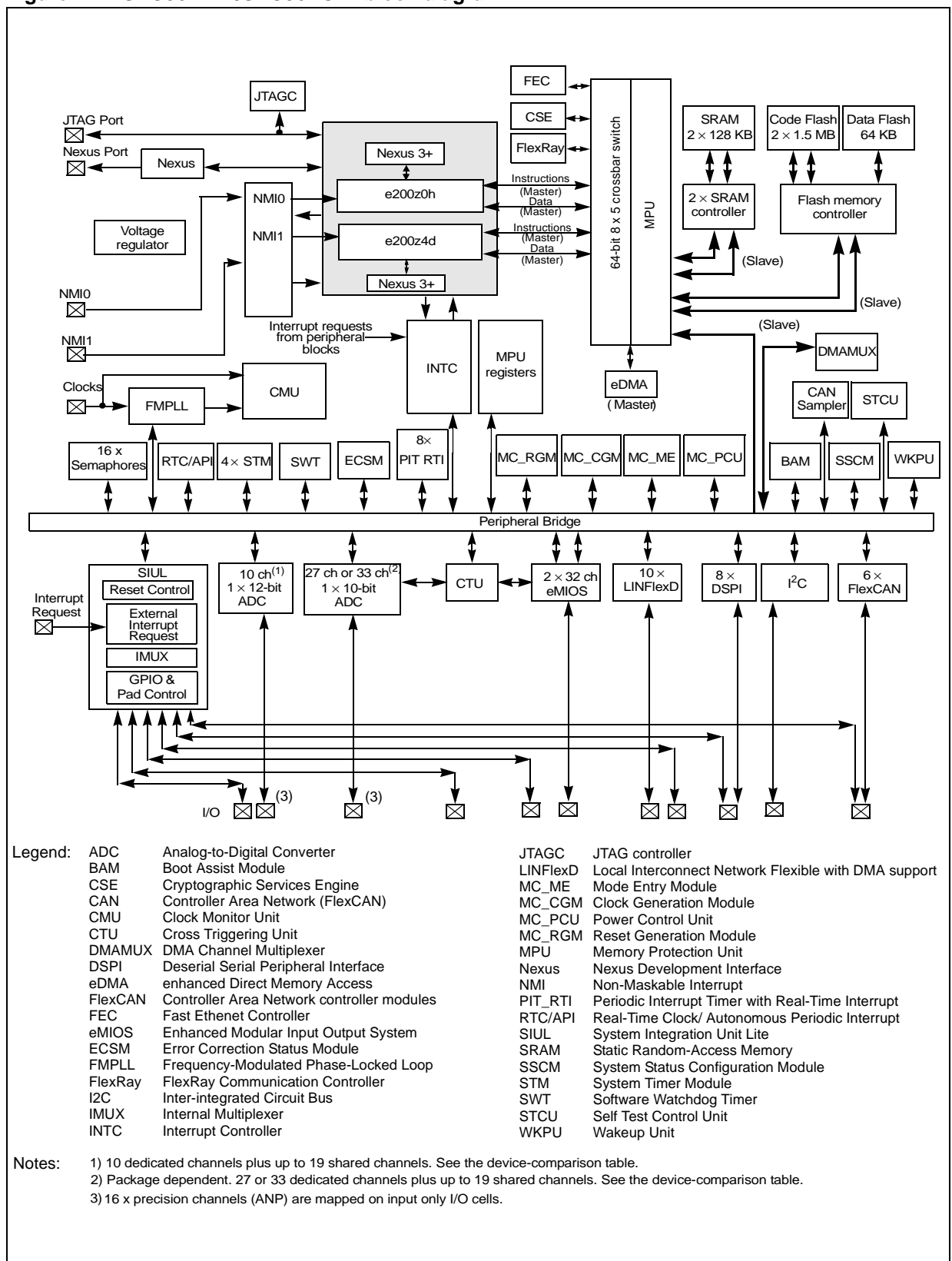
The e200z4d core has a Memory Management Unit (MMU)^(f) which prohibits access from the e200z4d core to the XBAR (Crossbar) unless a valid MMU entry is configured for that access.

The user has to take care that the MMU only protects access from the e200z4d core to the crossbar so that, it does not affect any of the other crossbar masters such as the e200z0h core, FlexRay or the eDMA (see [Figure 2](#)).

e. See section e200z4 core in RM0070 ([Section C.1: Reference document](#))

f. MMU is not present on e200z0h core

Figure 2. SPC564Bxx/SPC56ECxx block diagram



As previously described in the [Section 2.1: Boot mechanism](#) the MMU is not automatically configured^(g) apart from a small 4 KB page containing the reset vector address in the TLB entry 0.

This means that the MMU must be configured by the user, before any access outside to the block mapped by the SSCM.

In a typical application, the e200z4d core accesses Flash, SRAM and the peripheral blocks and therefore MMU access needs to be granted.

An example of configuration is showed in [Table 3](#).

This configuration is quite similar to the ones implemented in this application note with the exception of the SRAM 2 memory area (second row of the table). The relative TLB was not configured because this area is used by the performance core (e200z0h).

Note: The e200z4d core has 16 MMU TLB entries and these allow the user to increase if needed the protection granularity by splitting the memory in several blocks. For further information see Memory Protection Unit section in the Reference Manual (see [Section C.1: Reference document](#)).

Table 3. Example of MMU configuration

Memory area	Memory address	Size	Closest MMU size
SRAM 1	0x4000_0000 - 0x4001_FFFF	128KB	128KB
SRAM 2	0x4002_0000 - 0x4003_FFFF	128KB	128KB
Flash including shadow sector	0x0000_0000 - 0x00FF_FFFF	16MB	16MB
Peripherals	0xC000_0000 - 0xFFFF_FFFF	1GB	1GB

The user has to take into account setting up the stack (see [Section 3.1.3: Initialize the SRAM ECC](#)), prior to performing any RAM accesses like executing the mandatory ECC initialization, or before any peripheral register writes, the memory spaces have to be configured through the MMU entries.

These considerations both with small block (4KB) mapped by SSCM on TLB entry 0 by default (see [Section 2.1: Boot mechanism](#)) imply that all MMU regions have to be mapped at the start of the boot code.

MMU pages must not overlap and must also be configured on a boundary matching their size (for example, 4 KB MMU page must sit on a 4 KB boundary).

Moreover, it is strongly recommended that the user doesn't change the MMU configuration of a memory location currently being accessed, otherwise there is potential for errors.

The suggested order of MMU configuration could be defined as follows:

g. In this device family the Boot Assist Module (BAM) does not run when the device performs a normal Flash boot then the MMU configurations must be done by the user.

1. Configure the MMU TLB entry for RAM. In this manner, the user code can initialize the SRAM ECC (see [Section 3.1.3: Initialize the SRAM ECC](#)).
2. Configure the MMU TLB entry for Flash^(h) (see [Section 3.1.4: Configure MMU for Flash](#))
 - Copy configuration code to SRAM⁽ⁱ⁾
 - Jump to first instruction of this code in SRAM and execute it
 - Transfer execution back to the Flash
3. Configure the MMU TLB entry for the IPBridge (peripherals space) (see [Section 3.1.5: Configure MMU for Peripheral Bridge](#))

3.1.2 Configure MMU for SRAM

In order to configure MMU TLB entries, there are four MMU Assist registers (MAS) which are written with the TLB entry number, start address and size of the MMU entry and other information such as whether the page is VLE or BookE instructions.

In [Figure 3](#) is showed a scratch code of MMU configuration^(j) for RAM using TLB entry 1:

Figure 3. MMU configuration code for SRAM

```

#/******
#/* MMU configuration code for SRAM */
#/* TLB1, Entry 1 128KB 0x4000_0000 to 0x4001_FFFF */
#/******
    e_lis r3, 0x1001
    mtmas0 r3          #/* MAS0 */

    e_lis r3, 0xC000
    e_or2i r3, 0x0380
    mtmas1 r3          #/* MAS1 = 0xC0000380 (128Kb) */

    e_lis r3, 0x4000
    e_or2i r3, 0x0028
    mtmas2 r3          #/* MAS2 = 0x40000028 */

    e_lis r3, 0x4000
    e_or2i r3, 0x003F
    mtmas3 r3          #/* MAS3 = 0x4000003F */

    tlbwe              #/* Write the entry to the TLB */
    
```

The SRAM space mapped through the TLB 1 is half of the space available on the device^(k) and it corresponds to the bank placed at the lower addresses. The example shown here is using this as the upper bank is reserved for the e200z0h core.

- h. In this application note the strategy suggested is to re-uses the TLB 0 to map all Flash memory space.
- i. User can use this mechanism at this time (the execution from SRAM) to configure the wait states for Flash (see [Section 3.1.7: Performance Hints Initialization](#)): to avoid executing code from Flash while wait states are changing. This means that should copy also this configuration code to SRAM at this time and execute it with the MMU ones.
- j. After the MAS registers are written, the TLB is validated with a single “tlbwe” (TLB Write Entry) instruction
- k. This device family has two 128KB contiguous banks start at 0x4000_0000

This means that the e200z4d core doesn't need to have any mapping on this memory space (see [Section 1: Application example description](#)).

3.1.3 Initialize the SRAM ECC

The SRAM in the SPC564Bxx and SPC56ECxx family (as other SPC56xx devices) has the ECC (Error Correction Code) protection.

ECC checks are performed during the read portion of an SRAM ECC read/write (R/W) operation, and ECC calculations are performed during the write portion of a R/W operation. Because the ECC bits can contain random data after the device is powered on, the SRAM must be initialized by executing 32-bit write operations prior to any read accesses⁽¹⁾ to avoid ECC error and therefore an exception being raised.

[Figure 4](#) shows a scratch code of SRAM initialization.

Figure 4. SRAM ECC initialization code

```

/*****
/* Initialize all SRAM space by copying all 32GPR's to RAM (fast) */
/* Counter defines number of 32 x 32-bit words needed to write to RAM*/
*****/
e_lis r5, _SRAM_ADDR_Z4@h /* SRAM start address defined in the linker file */
e_or2i r5, _SRAM_ADDR_Z4@l

e_lis r6, _SRAM_SIZE_Z4@h /* SRAM size defined in the linker file */
e_or2i r6, _SRAM_SIZE_Z4@l

e_srwi r6, r6, 0x7 /* Divide SRAM size by 128 bytes */
mtctr r6 /* Move to counter for use with "bdnz" */

sram_loop:
e_stmw r0,0x0(r5) /* Write all 32 registers to SRAM */
e_addi r5,r5,128 /* Increment the RAM pointer to next */
/* 128byte(4bytes*32 registers) */
e_bdnz sram_loop /* Loop for all of SRAM */
    
```

3.1.4 Configure MMU for Flash

It is strongly recommended (see [Section 3.1.1: MMU remarks](#)), not to re-configure an MMU entry for memory that is currently being used because doing so that can cause stability issues at the point when the MMU TLB region is re-validated.

From the user point of view this means that it should be fine to configure additional TLB entries while executing from an existing entry.

Of course users could use the same TLB 0 to map all the Flash but the MMU configuration code must be executed by the SRAM: the code has to be copied to SRAM and then the execution flow is transferred to SRAM so that the Flash MMU entry can be safely re-configured (in this Application Note was described this strategy).

[Figure 5](#) shows a scratch code of MMU configuration for Flash using TLB entry 0.

1. This is also true for implicit read accesses caused by any write accesses of less than 32 bits

When the code is executed from Flash, all the code between the labels “conf_sram_code_begin” and “conf_sram_code_end” is copied^(m) to and executed from the SRAM.

Figure 6 shows a scratch code of copy code from Flash to SRAM.

Figure 5. MMU configuration code for Flash

```

#/******
#/* MMU configuration code for Flash (TLB1 entry 0) -> copy to RAM */
#/* TLB1 entry 0, 0x0000_0000 to 0x00FF_FFFF overwriting existing TLB */
#/* infact MMU have configured the small 4 KB block at the reset vector. */
#/* NOTE: this configuration allows access to all device Flash */
#/******
#/* ---- MMU configuration (TLB1, Entry 0) for Code Flash:this block will be
copied to RAM */
    e_lis r3, 0x1000          #/* MAS0, Configure TLB1, Entry 0 */
    mtmas0 r3
    e_lis r3, 0xC000          #/* MAS1 = 0xC0000700 (16MB) */
    e_or2i r3, 0x0700
    mtmas1 r3
    e_lis r3, 0x0000          #/* MAS2 = 0x00000020 */
    e_or2i r3, 0x0020
    mtmas2 r3
    e_lis r3, 0x0000          #/* MAS3 = 0x0000003F */
    e_or2i r3, 0x003F
    mtmas3 r3
    tlbwe                    #/* Write the entry to the TLB */

```

Figure 6. Code to copy configuration code from Flash to SRAM

```

conf_sram:
#/* Calculate number of bytes to copy (data between labels) */
    e_lis r3, conf_sram_code_begin@h
    e_or2i r3, conf_sram_code_begin@l
    e_lis r4, conf_sram_code_end@h
    e_or2i r4, conf_sram_code_end@l
    subf r4, r3, r4
    mtctr r4                #/* Move to counter register the number of bytes to copy */

    e_lis r5, _SRAM_ADDR_Z4@h #/* SRAM start address defined in the linker file */
    e_or2i r5, _SRAM_ADDR_Z4@l

copy_configuration_code:    #/* Copy configuration code from Flash to RAM */
    e_lbz r6, 0(r3)
    e_stb r6, 0(r5)
    e_addi r3, r3, 1
    e_addi r5, r5, 1
    e_bdnz copy_configuration_code#/* Loop is based on the value of counter */

    e_lis r24, _SRAM_ADDR_Z4@h #/* SRAM start address defined in the linker file*/
    e_or2i r24, _SRAM_ADDR_Z4@l

    se_mtctr r24
    se_bctr                #/* Jump to the SRAM Start address */

```

m. As mentioned previously, at this time, user can use this mechanism to configure also the Flash wait states (see [Section 3.1.7: Performance Hints Initialization](#)): he has to put the code between the labels.

3.1.5 Configure MMU for Peripheral Bridge

As mentioned user has to create a valid MMU entry before addressing any of the peripherals (including the SWT).

[Figure 7](#) shows a scratch code of MMU configuration⁽ⁿ⁾ for peripheral area TLB entry 2:

Figure 7. MMU configuration code for peripherals area

```

#/******
#/* MMU configuration code for Peripheral Area (IPBridge) */
#/* TLB1, entry 2 1GB 0xC000_0000 to 0xFFFF_FFFF */
#/******
e_lis r3, 0x1002      #/* MAS0, Configure TLB1, Entry 2 */
mtmas0 r3
e_lis r3, 0xC000     #/* MAS1 = 0xC0000A00 */
e_or2i r3, 0x0A00
mtmas1 r3
e_lis r3, 0xC000     #/* MAS2 = 0xC000002A */
e_or2i r3, 0x002A
mtmas2 r3
e_lis r3, 0xC000     #/* MAS3 = 0xC000003F */
e_or2i r3, 0x003F
mtmas3 r3

tlbwe                #/* Write the entry to the TLB */

```

3.1.6 Memory initialization

The Stack/Heap memory sections must be initialized as well as constants and pre-initialized variables being copied from Flash to RAM.

These initialization steps can be done by user by scratch or left to pre-built compiler initialization script (often hidden from user).

In any case these initialization steps are tightly coupled to the linker file and are compiler specific so it is not detailed in this document: GHS (GreenHills) compiler suite was used for this document (see [Figure 8](#)).

For this reason in the startup files described in these paragraphs (see [Appendix A: Application code example](#)) the label “_start” was substituted by “__ghs_board_memory_init” (see [Figure 9](#)) and at the end of the startup file the execution flow doesn’t branch to the application code (for example “e_bl main”) (see [Figure 10](#)) but instead it is redirected to GHS startup library which completes the memory initialization (for example, handle the SDA (Small Data Area) optimization).

n. After the MAS registers are written, the TLB is validated with a single “tlbwe” (TLB Write Entry) instruction

Figure 8. Booting flow using GHS startup libraries

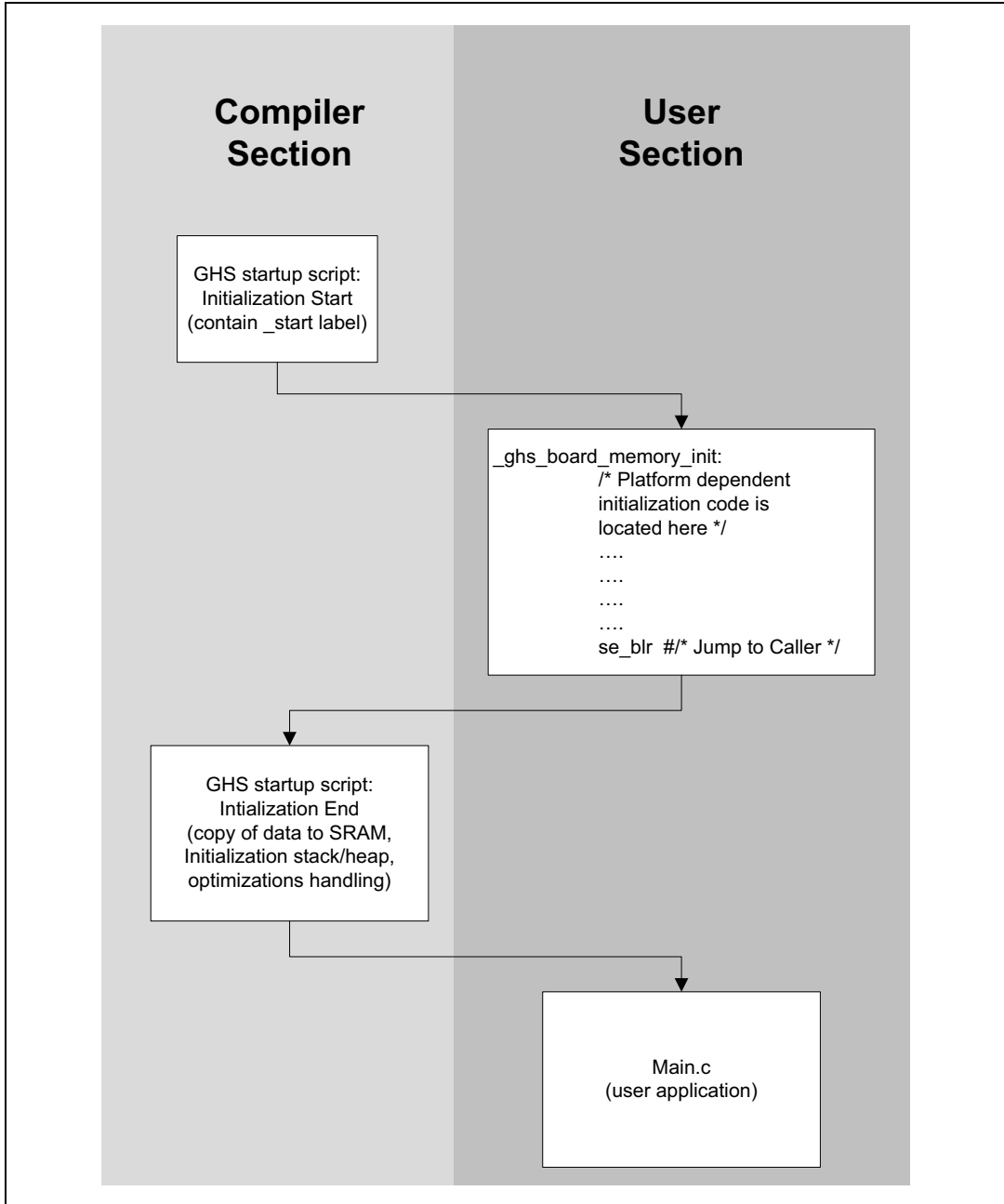


Figure 9. Startup file: __ghs_board_memory_init

```

#/******
#/* RCHW Configuration (and referencing of start label for linker) */
#/******
.section .rchw
.LONG 0x015A0000          /* RCHW: VLE bit, Valid Boood Identifier 0x5A */
.LONG _start
.file "crt0_corez4_Flash.s"

.section .vletext_boot, "vax"
.vle

#.global _start
.global __ghs_board_memory_init
.global asm_init_cache

.equ MPR0ADDR, 0xFFF04000
.equ MPR0VALUE, 0x76543210 /* Flash PORT1: Priority to corez4(instruct.)*
.equ SGPCR0VALUE, 0x0
.equ MPR1ADDR, 0xFFF04100
.equ MPR1VALUE, 0x76543201 /* Flash PORT1: Priority to corez4(data)*
.equ SGPCR1VALUE, 0x1
.equ MPR2ADDR, 0xFFF04200
.equ MPR2VALUE, 0x54376201 /* PRAM0: Priority to corez4(data)*
.equ SGPCR2VALUE, 0x1
.equ MPR3ADDR, 0xFFF04300
.equ MPR3VALUE, 0x54301276 /* PRAM1: Priority to corez0(data)*
.equ SGPCR3VALUE, 0x4
.equ MPR7ADDR, 0xFFF04700
.equ MPR7VALUE, 0x54327106 /* PBRIDGE: Priority to corez4(data)*
.equ SGPCR7VALUE, 0x1

/*_start: */          /* uncomment this line and comment the following one */
/* you don't use GHS libraries (take care to */
/* configure SDA/Stack/..pointers */
__ghs_board_memory_init:

```

Figure 10. Startup file: branch to GHS startup libraries

```

se_blr          /* Jump to Caller */

#e_bl main      /* Use this Branch and comment the previous if you not
                /* use GHS crt0.ppc */

.type __ghs_board_memory_init,@function
.size __ghs_board_memory_init,$-__ghs_board_memory_init

```

3.1.7 Performance Hints Initialization

The device performance can be addressed by customizing several system level configurations that of course need to be changed on user's application basis.

Below is a list of actions that user can done to speed up the device performances:

- Signal Processing Extension (SPE) for fixed point and single precision calculations (see [Figure 11](#));
- Branch Target Buffer (BTB) providing target address pre-fetching (see [Figure 11](#)): This enables operation beyond a conditional branch without waiting for the branch to be decoded and resolved;
- Flash Port Configuration. The user can choose to set the minimum wait states (with regard to device operating frequency) as well as configure the line buffer allocation and pre-fetch behavior.
In this application note the minimum allowed wait states for a device frequency equal to 120MHz, when prefetching enabled has been selected.(see [Figure 12](#));
- SRAM wait states: User has to setup an additional wait states over the SRAM (see [Figure 13](#)) if the system clock is above 64MHz.
In this application note it is preferred to insert this initialization (just to have all wait states configurations together) here even if this configuration is only strictly linked to system clock frequency (see [Section 3.2.3: Clock & PLL configuration](#)).
- The highly configurable crossbar (XBAR) architecture allows tailored priorities and arbitration schemes on a per slave port basis. For detailed information please refer to the XBAR chapter in the Reference Manual (see [Section C.1: Reference document](#)).
In this application note it has been selected to configure the XBAR so that the e200z4d core execution can have the maximum priority over all other slaves ([Figure 14](#)).
All the configurations related to XBAR (for example: all the masters) are done inside the startup file of the e200z4d core even if no special constraints are present. This implementation has been chosen to have all XBAR configurations together.
Note how the slave 3 (the slave port related to PRAM controller one) is configured to give priority to e200Z0h (see [Section 1: Application example description](#));
- Configure the ICache. The e200z4d processor supports a 4 Kbyte, 2 or 4-way set-associative, instruction cache (ICache) with a 32-byte line size.
The ICache improves system performance by providing low-latency data to the instruction pipeline. In this application note the 4-way configuration, which generally allows the best performance versus the 2-way ones, has been chosen (see [Figure 16](#)).
Note that this code is located in the startup file (as an assembly function) but isn't executed at this time (see [Section 3.2.4: Configure Cache](#)).

Figure 11. Startup file: enable BTB and SPE

```

#/******
#/* Enable Signal Processing extension (SPE) in Machine State Register */
#/******
mfMSR r3
e_or2isr3, 0x0200
mtMSR r3
#/******
#/* Enable Branch Target Buffers BTB */
#/******
e_li r0, 0x201
mtspr1013, r0

```

Figure 12. Startup file: Flash Configuration code

```

#/******
#/* Configure the Flash wait states and the prefetch buffers -> copy to RAM*/
#/* Code is copied to RAM first, then executed, to avoid executing code */
#/* from Flash while wait states are changing. */
#/******
#/* PFCR0 = 0x294BFDFD (settings for 120MHz) */
#/* APC and RWSC = 0b101 (5 additional hold cycles) */
#/* WWSR = 0b101 (5 wait) */
#/* B02_P0_DPFE = 0b1 (enabled) */
#/* B02_P0_IPFE = 0b1 (enabled) */
#/* B02_P0_PFLIM = 0b1x (prefetch on miss or hit) */
#/* B02_P0_BFE = 0b1 (enabled) */

e_lis r3, 0x294B
e_or2i r3, 0xFDFD /* NOTE: 0xaDaD = 0xaFaF */

e_lis r4, 0xC3F8 /* PFCR0 ADDRESS HIGH */
e_or2i r4, 0x801C /* PFCR0 ADDRESS LOW */
e_stw r3, 0(r4)
se_isync
msync

#/* PFAPR = 0x0300FFFF */
e_lis r3, 0xFF00 /* Round-robin arbitration-Prefetching enabled. */
e_or2i r3, 0xFFFF /* Both read and write accesses */
e_lis r4, 0xC3F8 /* PFAPR ADDRESS HIGH */
e_or2i r4, 0x8024 /* PFAPR ADDRESS LOW */
e_stw r3, 0(r4)
se_isync
msync

```

Figure 13. Startup file: SRAM wait states configuration code

```

#/******
#/* Configure SRAM wait states to 1 */
#/* RAM needs an additional wait state if the system clock is above 64 Mhz */
#/******
e_lis r3, 0x4000 /* 1-wait state for RAM access */
e_or2i r3, 0x0

e_lis r4, 0xFFF4 /* ECSM */
e_or2i r4, 0x0024
e_stw r3, 0(r4)
se_isync
msync

```

Figure 14. Startup file: XBAR register configuration values

```
.equ MPR0ADDR, 0xFFFF04000
.equ MPR0VALUE, 0x76543210 /* Flash PORT1: Priority to corez4(instruct.)*/
.equ SGPCR0VALUE, 0x0
.equ MPR1ADDR, 0xFFFF04100
.equ MPR1VALUE, 0x76543201 /* Flash PORT1: Priority to corez4(data)*/
.equ SGPCR1VALUE, 0x1
.equ MPR2ADDR, 0xFFFF04200
.equ MPR2VALUE, 0x54376201 /* PRAM0: Priority to corez4(data)*/
.equ SGPCR2VALUE, 0x1
.equ MPR3ADDR, 0xFFFF04300
.equ MPR3VALUE, 0x54301276 /* PRAM1: Priority to corez0(data)*/
.equ SGPCR3VALUE, 0x4
.equ MPR7ADDR, 0xFFFF04700
.equ MPR7VALUE, 0x54327106 /* PBRIDGE: Priority to corez4(data)*/
.equ SGPCR7VALUE, 0x1
```

Figure 15. Startup file: XBAR configuration code^(o)

```

#/******
#/* Configure XBAR */
#/******
#/* Configure Master Priority Register 0 */
e_lis r4, MPR0VALUE@h      /* MPR0 Conf. High Value */
e_or2i r4, MPR0VALUE@l    /* MPR0 Conf. Low Value */

e_lis r5, MPR0ADDR@h      /* MPR0 Address High Value */
e_or2i r5, MPR0ADDR@l    /* MPR0 Address Low Value */
se_stw r4,0x0(r5)        /* Store Value */

#/* Configure Slave General Purpose Control Register 0 */
e_lis r4, SGPCR0VALUE@h   /* SGPCR0 High Value High Value */
e_or2i r4, SGPCR0VALUE@l /* SGPCR0 Low Value */

se_stw r4,0x10(r5) /* Store Value (SGPCR0 address is 0x10 bytes after MPR0)*/

#/* Configure Master Priority Register 1 */
e_lis r4, MPR1VALUE@h   /* MPR1 Conf. High Value */
e_or2i r4, MPR1VALUE@l /* MPR1 Conf. Low Value */

e_lis r5, MPR1ADDR@h   /* MPR1 Address High Value */
e_or2i r5, MPR1ADDR@l /* MPR1 Address Low Value */
se_stw r4,0x0(r5)     /* Store Value */

#/* Configure Slave General Purpose Control Register 1 */
e_lis r4, SGPCR1VALUE@h /* SGPCR1 High Value High Value */
e_or2i r4, SGPCR1VALUE@l /* SGPCR1 Low Value */

se_stw r4,0x10(r5) /* Store Value (SGPCR1 address is 0x10 bytes after MPR1)*/

#/* Configure Master Priority Register 2 */
e_lis r4, MPR2VALUE@h   /* MPR2 Conf. High Value */
e_or2i r4, MPR2VALUE@l /* MPR2 Conf. Low Value */

e_lis r5, MPR2ADDR@h   /* MPR2 Address High Value */
e_or2i r5, MPR2ADDR@l /* MPR2 Address Low Value */
se_stw r4,0x0(r5)     /* Store Value */

#/* Configure Slave General Purpose Control Register 2 */
e_lis r4, SGPCR2VALUE@h /* SGPCR2 High Value High Value */
e_or2i r4, SGPCR2VALUE@l /* SGPCR2 Low Value */

se_stw r4,0x10(r5) /* Store Value (SGPCR2 address is 0x10 bytes after MPR1)*/

```

o. XBAR configuration not fully showed in this picture.

Figure 16. Cache Configuration Code

```
#####  
# invalidate and enable the instruction cache (4WAY)  
#####  
asm_init_cache:  
    e_lis r3, 0x0  
    e_or2i r3,0x0002  
    mtllcsr1 r3  
  
    loop_invalid_cache:  
    msync  
    mfllcsr1 r3  
    e_and2i.r3,2  
    se_bne loop_invalid_cache  
  
# inst cache enable (4way)  
    e_lis r3, 0x0  
    e_or2i r3, 0x0011    #(use 0x0001 for 2way)  
    mtllcsr1 r3  
  
    se_blr
```

3.2 e200z4d device configuration from C code

Before the execution of the application code, user has to complete the device initialization by performing the following steps (see [Figure 17](#)):

1. Disable the SWT (Software Watchdog Timer) (see [Section 3.2.1: Disable watchdog](#));
2. Configure device modes (see [Section 3.2.2: Mode configuration and clocking](#));
3. Configure system dividers (see [Section 3.2.3: Clock & PLL configuration](#));
4. Configure PLL (Phase Locked Loop) (see [Section 3.2.3: Clock & PLL configuration](#));
5. Enable Instruction cache (see [Section 3.2.4: Configure Cache](#));
6. Start e200z0h core (see [Section 3.2.5: Starting the e200z0h core](#));

Figure 17. Environment configurations code

```
void Environment_Init(void){
    SWT_Disable();           /* Disable Software Watchdog Timer (Can */
                           /* also be disabled in Shadow row) */

    MODE_Init();            /* Configure modes and activate all clocks */
                           /* for all peripherals */

    CGM.Z0_DCR.B.DIV = 0x1; /* Z0 clock divider to divide by 2 */
    CGM.Flash_DCR.B.DIV = 0x1; /* Flash register interface /2 (default) */

    PLL_Init();             /* Set system clock to 120MHz */
                           /* based on 40Mhz XTAL */

    asm_init_cache();       /* Enable Cache 4WAY */

    /* Start Z0 Core */
    SSCM.DPMBOOT.R = 0x00180000; /* Start address of Z0 (2nd Flash block) */
    SSCM.DPMKEY.R = 0x00005AF0; /* Write key 1 */
    SSCM.DPMKEY.R = 0x0000A50F; /* Write key 2 */
}
```

3.2.1 Disable watchdog

The Software Watchdog Timer (SWT)^(p) is a peripheral module that can prevent system lockup in situations such as software getting trapped in a loop or if a bus transaction fails to terminate.

When enabled, the SWT requires periodic execution of a watchdog servicing operation: in order to prevent a system reset, the watchdog must be serviced or disabled prior to the initial expiry of the timer.

In a real application it is expected that the SWT would be serviced (before it expires) and re-configured to match application timing rather than being disabled.

Look at Reference Manual ([Section C.1: Reference document](#)) for more information on configuring and using the SWT.

In this document, the watchdog is disabled to avoid any servicing.

p. The SWT is clocked from the Slow Internal Reference Clock (SIRC) with a nominal frequency of 128 KHz. The default SWT timeout is set to approximately 10 ms: this timeout period is determined by the actual SIRC frequency which varies over temperature according to the device specification.

The simplest way to disable the SWT is to do it at the start of the main program once all of the initialization code has been executed. The user has to take care that there is enough time (versus the SWT time period) between the start of initialization code (startup code) and the main function.

If there is any doubt over the time taken to run the initialization code, the watchdog can be addressed as soon as the MMU page is defined for the peripherals.

In order to disable the watchdog in software the user needs to:

- Write the sequence of 0xC520 followed by 0xD928 to the service register. This clears the soft lock bit enabling the next step in the process;
- Clear the WEN bit in the Control register;

Figure 18. SWT disabling code

```
void SWT_Disable(void)
{
    SWT.SR.R = 0xC520; /* Clear Soft lock bit in CR by writing */
    SWT.SR.R = 0xD928; /* 0xC520 followed by 0xD928 to WSC field */
    SWT.CR.B.WEN = 0x0; /* Clear Watchdog Enable Bit */
}
```

Note: When user is connecting to the device using a debugger, it is likely that the debugger itself disables the watchdog to allow debug to be carried out. This can result in a fairly common problem when attempting to run the code in a standalone configuration where a periodic device reset is observed, caused by the SWT time-out.

It's possible to use an additional way to disable the SWT at device reset by writing to the Non Volatile User Options (NVUSRO) register located in the shadow row at address 0x00FF_FE18.

By disabling the watchdog^(q) in this manner it can then be re-enabled at a later stage if desired.

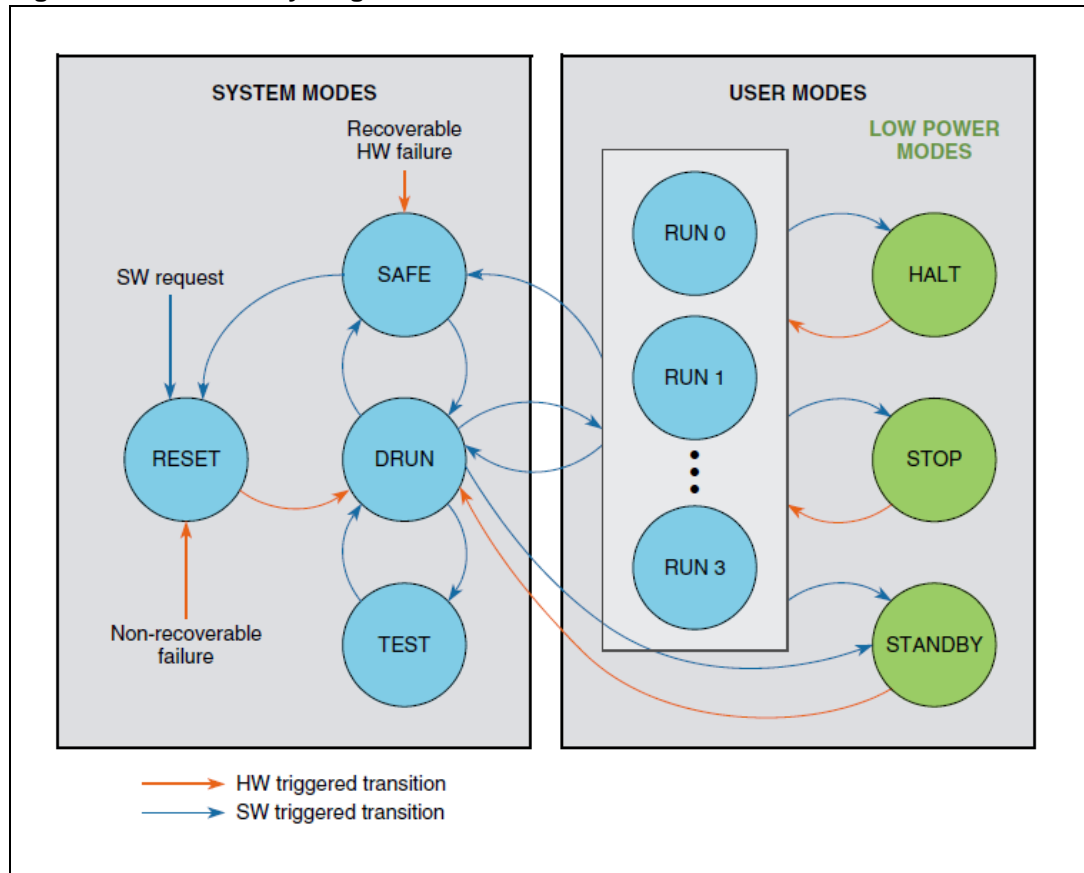
- If bit-0 (MSB) of NVUSRO is set, as with an erased shadow Flash, then the SWT is enabled
- If bit-0 of NVUSRO is cleared, then the SWT is disabled

3.2.2 Mode configuration and clocking

The SPC564Bxx and SPC56ECxx device family (as other SPC56xx devices) has several operating modes (see [Section C.1: Reference document](#)). Out of reset the device leaves the Reset mode and enters DRUN mode (see [Figure 19](#)).

q. If no valid RCHW is found by the SSCM, the watchdog is re-enabled (even if the SWT is disabled in the NVUSRO register) before the device enters Static mode (see [Section 2.1: Boot mechanism](#)).

Figure 19. Mode entry diagram



In order to use all of the available modes, they must be enabled in the Mode Enable register (see [Figure 20](#)).

Figure 20. Mode Initialization Code

```

void MODE_Init(void)
{
    ME.MER.R = 0x000025FF;           /* Enable all modes */
    ME.RUNPC[0].R = 0x000000FE;     /* Enable all peripherals in all modes */

    /* Enable system clock for all peripherals assuming 120MHz system clock */
    CGM.SC_DC[0].R = 0x83;          /* Max 32MHz. Closest is 30MHz, Div+1=3 */
    CGM.SC_DC[1].R = 0x81;          /* Max 64MHz. Closest is 60MHz, Div+1=2 */
    CGM.SC_DC[2].R = 0x81;          /* Max 64MHz. Closest is 60MHz, Div+1=2 */

    /* Re-enter DRUN mode to update the clock configuration */
    ME.MCTL.R = 0x30005AF0;         /* DRUN Mode & Key */
    ME.MCTL.R = 0x3000A50F;         /* DRUN Mode & Key */

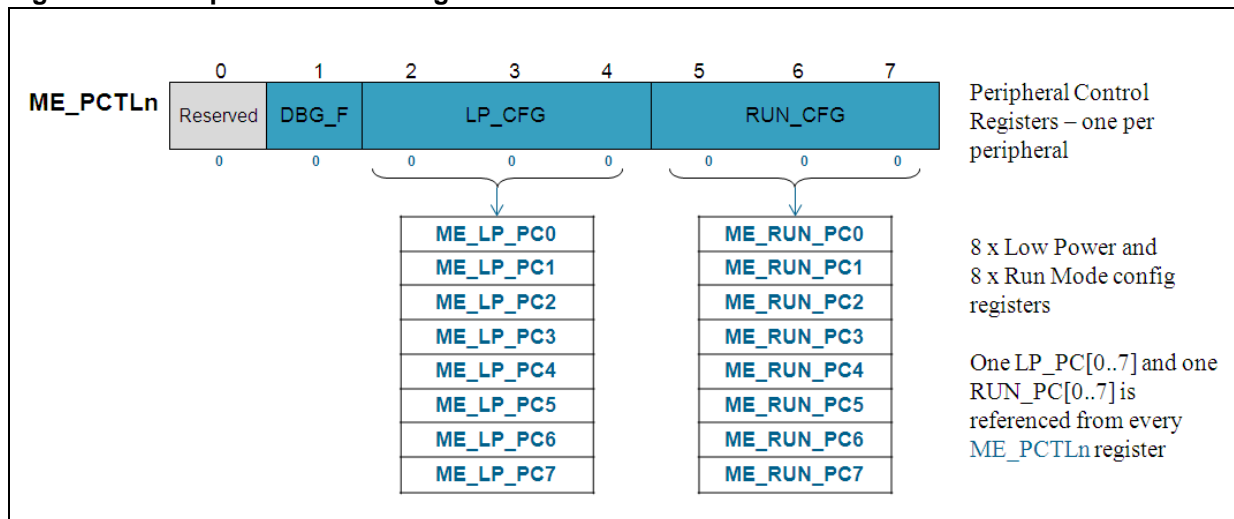
    while (ME.GS.B.S_MTRANS == 1); /* Wait for mode transition complete */
}
    
```

Every peripheral (see [Figure 21](#)) has an associated control register which has 3 fields to determine what happens when the MCU is in the following modes:

- Debug mode (DBG_F)
- Low Power mode (LP_CFG)
- Run Mode (RUN_CFG)

For Low Power and Run modes there are 8 sets of configuration registers that are referenced by the LP_CFG and RUN_CFG fields from the peripheral control registers. Each of these configuration registers have a bit for each Run or Low Power mode which determines whether the peripherals referencing this register are clock gated or available in that mode: this allows up to 8 different power schemes to be created with a different mix of peripherals to be available in each Low Power or Run mode.

Figure 21. Peripheral Control Registers



Out of reset, all of the peripheral control registers have value 0x0 which means they are associated with ME_RUN_PC0 for Run modes (and ME_LP_PC0 for Low Power modes). Setting ME_RUN_PC0 to 0x0000_00FE (see [Figure 22](#)), enables all peripherals in all Run modes which is the baseline configuration used in this example (see [Figure 20](#)).

Figure 22. Run peripheral control registers

	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
R	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
W																
Reset	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	16	17	18	19	20	21	22	23	24	25	26	27	28	29	30	31
R	0	0	0	0	0	0	0	0	RUN3	RUN2	RUN1	RUN0	DRUN	SAFE	TEST	RESET
W																
Reset	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

There are 3 peripheral clock groups on the SPC564Bxx and SPC56ECxx device family with associated clock dividers. These allow all 3 peripheral clock groups independent clock control so groups can be slowed down or even clock gated which helps with power saving. For more details and for peripheral assignments, refer to the device Reference Manual (see [Section C.1: Reference document](#)).

Peripheral group 1 can be clocked at a maximum of 32 kHz, peripheral groups 2 and 3 can run at a maximum of 64 kHz. Care needs to be taken not to exceed these limits (see [Figure 20](#)).

Note: A peripheral clock group has to be specifically enabled or the peripherals is not accessible. For the purpose of this example, all of the peripheral clock groups are enabled by writing to the associated system clock divider registers even though all are not required.

Finally, in line with all clock and mode configuration, a mode transition must be made for all the above changes to take effect.

For further information look at Mode Entry Module chapter in the device Reference Manual (see [Section C.1: Reference document](#)).

In this case, DRUN mode is re-entered by writing a mode and key command sequence (see [Figure 20](#)).

3.2.3 Clock & PLL configuration

The SPC564Bxx and SPC56ECxx device family is clocked by default from the 16 MHz IRC. In order to attain the maximum performance of the device, the system clock speed needs to be increased, up to 120 Mhz for the maximum system clock.

The device has several functional blocks that run at different frequency and for this reason before the system clock is changed the user has to take some constraints into account (the individual clock dividers must be set accordingly) to allow the device to run up to the maximum of 120 MHz:

- The e200z0h core has a maximum clock speed of 80 Mhz;
- The FEC (Fast Ethernet Controller) requires its clock divider to be /2 if system clock is > 80 MHz;
- The Flash register interface has a maximum operating frequency of 80 Mhz;
- The RAM needs an additional wait state if the system clock is above 64 Mhz;

Note: The FEC is not used so in this case the divider is left at its default value.

Figure 23. System clock dividers configuration code^(r)

```
CGM.Z0_DCR.B.DIV = 0x1;      /* Z0 clock divider to divide by 2 */
CGM.Flash_DCR.B.DIV = 0x1;  /* Flash register interface /2 (default) */
```

At this time the PLL can be used to change the system clock to the desired level (see [Figure 24](#)).

Note: All of the clock and PLL re-configuration can be achieved with a single mode re-entry but there is also an option to effect a mode re-entry for each critical step in the process. It allows an easy debug if the steps fail, in this way the problem can be identified easily.

r. In this application note the SRAM wait states configuration is done in the initialization code at startup (see [Section 3.1.7: Performance Hints Initialization](#))

Figure 24. PLL configuration code

```

void PLL_Init(void) {
    ME.DRUN.B.FXOSC00N = 1;          /* Switch on external oscillator in DRUN mode */
    /* Re-Enter DRUN mode (mode=0x3) to activate change */
    ME.MCTL.R = 0x30005AF0;          /* Mode & Key */
    ME.MCTL.R = 0x3000A50F;          /* Mode & Key inverted */
    while(ME.GS.B.S_MTRANS == 1);    /* Wait for mode transition complete */
    while(ME.GS.B.S_CURRENTMODE != 3); /* Error trap - if current mode is not */

                                        /* DRUN(eg in safe mode), then loop */
    while(ME.GS.B.S_FXOSC != 1);     /* Wait for external OSC to stabilize */

    /* Select External OSC as the FMPLL Reference Clock Source */
    CGM.AC0_SC.B.SELCTL = 0x0;

    /* Configure PLL for 120MHz with 40MHz xtal: */
    /* PLL frequency = (40 * NDIV)/(IDF * ODF) */

    /* NOTE: VCO (PLL * ODF) must be between 256 and 512MHz */
    CGM.FMPLL_CR.B.IDF = 0x4;        /* Divide by 5 */
    CGM.FMPLL_CR.B.ODF = 0x1;        /* Divide by 4 */
    CGM.FMPLL_CR.B.NDIV = 60;        /* Divide by 60 */

    /* Enable PLL in DRUN mode. */
    ME.DRUN.B.FMPLLON = 1;
    /* Re-Enter DRUN mode (mode=0x3) to activate change */
    ME.MCTL.R = 0x30005AF0;          /* Mode & Key */
    ME.MCTL.R = 0x3000A50F;          /* Mode & Key inverted */
    while(ME.GS.B.S_MTRANS == 1);    /* Wait for mode transition complete */

    while(ME.GS.B.S_CURRENTMODE != 3); /* Error trap - if current mode is not */
    /* DRUN(eg safe mode), then loop */
    while(CGM.FMPLL_CR.B.S_LOCK == 0); /* wait for PLL to lock (will not lock */
                                        /* until re-enter DRUN mode */

    /* Finally set system clock to be PLL in DRUN mode */
    ME.DRUN.B.SYSCLK = 0x4;
    /* Re-Enter DRUN mode (mode=0x3) to activate change */
    ME.MCTL.R = 0x30005AF0;          /* Mode & Key */
    ME.MCTL.R = 0x3000A50F;          /* Mode & Key inverted */
    while(ME.GS.B.S_MTRANS == 1);    /* Wait for mode transition complete */
    while(ME.GS.B.S_CURRENTMODE != 3); /* Error trap - if current mode is not */
                                        /* DRUN (eg safe mode), then loop */
    while(ME.GS.B.S_SYSCLK != 4){};   /* Final check - ensure ME_GS reports clk */
                                        /* as system PLL(0x4) - fail if stuck here */

    /* Enable CLKOUT pin so clock frequency can be verified */
    CGM.OC_EN.B.EN = 1;              /* Enable Output clock */
    CGM.OCDS_SC.R = 0x23000000;      /* And select output as system clock / 4 */
    SIU.PCR[0].R = 0x0A04;           /* PA0 ALT2 function (Clkout), MAX SRC */
}

```

3.2.4 Configure Cache

The e200z4d processor supports a 4 Kbyte, 2 or 4-way set-associative, instruction cache (ICache) with a 32-byte line size. The cache, as it is easy to understand, speeds up the device performances because it decouples processor performance from system memory performance (see [Section 3.1.7: Performance Hints Initialization](#)).

In this application note, the 4-way mode has been chosen because it allows better performance with respect to the 2-way mode.

Even if this initialization is strictly linked to performance increase, it's recommended to enable it after the clocks because there is no telling what the Cache Controller or the Tag/Data arrays do if their clock is changed. Look at section *e200z4d Core in RM0070* for details (see [Section C.1: Reference document](#)).

3.2.5 Starting the e200z0h core

After a reset, the e200z0h core is held in reset until it is released by writing a sequence of registers from the e200z4d core:

- Write the e200z0h boot (start) address^(s) to the SSCM DPM Boot.
- Write 0x0000_5AF0 to the SSCM DPM Boot Key register
- Write 0x0000_A50F to the SSCM DPM Boot Key register

After the execution of the sequence (see [Figure 17](#)), the e200z0h executes code from the start address defined in the DPM Boot register.

Any subsequent reset of the MCU results in the e200z0h being held in reset until the sequence is carried out again by the e200z4d core.

Note: If the e200z0h starting sequence is not performed well the device works (as single core) only with e200z4d core.

s. This address has to be 4 byte aligned as the lower 2 bits in the BPM boot register are reserved and set to 0b00

3.3 The e200z4d example code

After the basics initialization (see [Section 3.2: e200z4d device configuration from C code](#)), the user configures the output pin (PE[4]) on which is connected a led (see [e200z4d Core in RM0070](#), see [Section C.1: Reference document](#)), the e200z4d core toggles the pin and then loops forever (see [Figure 25](#)).

In the meantime, the e200z0h core executes a similar code to toggle a led through a contiguous port pin.

Figure 25. Application code: the main function

```
int main(int argc, char *argv[]){

    Environment_Init();                               /* Basic device Initilaizations */
                                                    /* (Modes,Pll,Start core 1,...) */

    /* Example Code start here */
    /* Loop forever Flashing an LED connected to Port PE[4] */
    /* (core Z0 code blink contiguous led) */
    SIU.PCR[PIN_NUMBER].R = 0x0200;                 /* PE[4] to GPIO mode, output */

    while(1){
        /* Invert LED output */
        SIU.GPDO[PIN_NUMBER].R = ~(SIU.GPDO[PIN_NUMBER].R & 0x01);
        for (count=0; count<1000000; count++);    /* wait a while */
    };
    return 0;

} /* End Of Main */
```

4 e200z0h Initializations and example code

The e200z0h core executes code from the start address defined in the DPM boot register after the execution of the three write sequences over the SSCM registers (see [Section 3.2.5: Starting the e200z0h core](#)).

As previously mentioned in this application note, with the exception of XBAR (see [Section 3.1.7: Performance Hints Initialization](#)), the initialization code for the cores are executed separately^(t) and it means that the e200z0h has its own startup file (see [Section 4.1: e200z0h startup code](#)).

4.1 e200z0h startup code

The startup code for the e200z0h is very simple because the user has to configure only few topics.

The e200z0h is activated by the e200z4d core and for this reason the microcontroller doesn't follow the normal boot sequence as for the primary core (see section *e200z4d Core in RM0070* see [Section 2.1: Boot mechanism](#)): this implies that there is no RCHW section in the code (see [Figure 26](#)).

Whereas the e200z0h core doesn't have either MMU, nor cache and considering the device initializations done by e200z4d core (see [Section 3: e200z4d initialization and example code](#)), the initialization code has to perform only two actions (see [Figure 26](#)):

1. Initialize SRAM ECC (second block) (see [Section 3.1.3: Initialize the SRAM ECC](#));
2. Enable BTB (Branch Target Buffer) for the e200z0h core (see [Section 3.1.7: Performance Hints Initialization](#)).

t. In order to simplify the work to the user it was suggested to have two separate projects for the two cores.

Figure 26. e200z0h startup code

```

.LONG _start
.file "crt0_corez0_Flash.s"

.section .vletext_boot, "vax"
.vle

#.global _start
.global __ghs_board_memory_init

__ghs_board_memory_init:

#/******
#/* Initialize all SRAM space by copying all 32GPR's to RAM (fast) */
#/* Counter defines number of 32 x 32-bit words needed to write to RAM */
#/******
    e_lis    r5, _SRAM_ADDR_Z0@h /* SRAM start address defined in the Locator */
    e_or2i  r5, _SRAM_ADDR_Z0@l

    e_lis    r6, _SRAM_SIZE_Z0@h /* SRAM size defined in the Locator */
    e_or2i  r6, _SRAM_SIZE_Z0@l

    e_srwi  r6, r6, 0x7          /* Divide SRAM size by 128 bytes */
    mtctr  r6                  /* Move to counter for use with "bdnz" */

sram_loop:
    e_stmw  r0,0x0(r5)          /* Write all 32 registers to SRAM */
    e_addi  r5,r5,128           /* Increment the RAM pointer to next 128byte */
                                           /* (4bytes*32 registers) */

    e_bdnz  sram_loop          /* Loop for all of SRAM */

#/******
#/* Enable Branch Target Buffers BTB */
#/******
    e_lir0, 0x201
    mtspr1013, r0

    se_blr                                /* Jump to Caller */

    #e_bl main                            /* Use this Branch and comment the previous */
                                           /* if you not use GHS crt0.ppc */

.type __ghs_board_memory_init,@function
.size __ghs_board_memory_init,$-__ghs_board_memory_init

##-----

```

Appendix A Application code example

The example application code for e200z4d core discussed in this application note is available for the user to use directly from the following pages.

Note that the formatting and alignment is configured for a normal text editor so the formatting should be correctly aligned when pasted into a standard text editor with normal spacing.

A.1 main.c file

```
#include "typedefs.h"
#include "MPC5646x.h"

#ifdef __cplusplus
extern "C" {
#endif

/*****
| external declarations
|-----*/
extern asm_init_cache(void);
/*****
| defines and macros (scope: module-local)
|-----*/
/*****
| typedefs and structures (scope: module-local)
|-----*/
/*****
| global variable definitions (scope: module-exported)
|-----*/
/*****
| global variable definitions (scope: module-local)
|-----*/
uint32_t count; /* counter used in delay loop */
const int PIN_NUMBER = 68; /* PE4 */
/*****
| function prototypes (scope: module-local)
|-----*/
static void SWT_Disable(void);
static void MODE_Init(void);
static void PLL_Init(void);
static void Environment_Init(void);
/*****
| function implementations (scope: module-local)
|-----*/
/***** void SWT_Disable(void) *****/
//! This function disable the software watchdog
/*!

\brief Disable Software Watchdog Timer
\return No return value.
\retval void

\note Can also be disabled in Shadow row
*/
void SWT_Disable(void)
{
```

```

    SWT.SR.R = 0xC520; /* Clear Soft lock bit in CR by writing */
    SWT.SR.R = 0xD928; /* 0xC520 followed by 0xD928 to WSC field */
    SWT.CR.B.WEN = 0x0; /* Clear Watchdog Enable Bit */
}
/***** void MODE_Init(void) *****/
//! This function initialize the modes
/*!

\brief Enable system clock for all peripherals assuming 120MHz system cloc
\return No return value.
\retval void

\note None
*/
void MODE_Init(void)
{
    ME.MER.R = 0x000025FF; /* Enable all modes */
    ME.RUNPC[0].R = 0x000000FE; /* Enable all peripherals in all modes */

    /* Enable system clock for all peripherals assuming 120MHz system clock */
    CGM.SC_DC[0].R = 0x83; /* Max 32MHz. Closest is 30MHz, Div+1=3 */
    CGM.SC_DC[1].R = 0x81; /* Max 64MHz. Closest is 60MHz, Div+1=2 */
    CGM.SC_DC[2].R = 0x81; /* Max 64MHz. Closest is 60MHz, Div+1=2 */

    /* Re-enter DRUN mode to update the clock configuration */
    ME.MCTL.R = 0x30005AF0; /* DRUN Mode & Key */
    ME.MCTL.R = 0x3000A50F; /* DRUN Mode & Key */

    while (ME.GS.B.S_MTRANS == 1); /* Wait for mode transition complete */
}
/***** void PLL_Init(void) *****/
//! This function configure the PLL
/*!

\brief This function configure the PLL
\return No return value.
\retval void

\note Switch on osc, change mode and wait for osc ON
Configure and enable PLL, change mode and wait for PLL to lock
Set clock source as PLL, change mode and check clock is PLL
*/
void PLL_Init(void){

    ME.DRUN.B.FXOSC0ON = 1; /* Switch on external oscillator in DRUN mode */
    /* Re-Enter DRUN mode (mode=0x3) to activate change */
    ME.MCTL.R = 0x30005AF0; /* Mode & Key */
    ME.MCTL.R = 0x3000A50F; /* Mode & Key inverted */
    while (ME.GS.B.S_MTRANS == 1); /* Wait for mode transition complete */
    while (ME.GS.B.S_CURRENTMODE != 3); /* Error trap - if current mode is not DRUN (eg
in safe mode), then loop */
    while (ME.GS.B.S_FXOSC != 1); /* Wait for external OSC to stabilize */

    /* Select External OSC as the FMPLL Reference Clock Source */
    CGM.AC0_SC.B.SELCTL = 0x0;

    /* Configure PLL for 120MHz with 40MHz xtal: PLL frequency = (40 * NDIV) / (IDF *
ODF) */
    /* NOTE: VCO (PLL * ODF) must be between 256 and 512MHz */
    CGM.FMPLL_CR.B.IDF = 0x4; /* Divide by 5 */
    CGM.FMPLL_CR.B.ODF = 0x1; /* Divide by 4 */
    CGM.FMPLL_CR.B.NDIV = 60; /* Divide by 60 */

    /* Enable PLL in DRUN mode. */

```

```

ME.DRUN.B.FMPLLON = 1;
/* Re-Enter DRUN mode (mode=0x3) to activate change */
ME.MCTL.R = 0x30005AF0; /* Mode & Key */
ME.MCTL.R = 0x3000A50F; /* Mode & Key inverted */
while(ME.GS.B.S_MTRANS == 1); /* Wait for mode transition complete */
while(ME.GS.B.S_CURRENTMODE != 3); /* Error trap - if current mode is not DRUN (eg
safe mode), then loop */
while(CGM.FMPLL_CR.B.S_LOCK == 0); /* wait for PLL to lock (will not lock until re-
enter DRUN mode */

/* Finally set system clock to be PLL in DRUN mode */
ME.DRUN.B.SYSCLK = 0x4;
/* Re-Enter DRUN mode (mode=0x3) to activate change */
ME.MCTL.R = 0x30005AF0; /* Mode & Key */
ME.MCTL.R = 0x3000A50F; /* Mode & Key inverted */
while(ME.GS.B.S_MTRANS == 1); /* Wait for mode transition complete */
while(ME.GS.B.S_CURRENTMODE != 3); /* Error trap - if current mode is not DRUN (eg
safe mode), then loop */
while(ME.GS.B.S_SYSCLK != 4){}; /* Final check - ensure ME_GS reports clock as
system PLL (0x4) -- fail if stuck here */

/* Enable CLKOUT pin so clock frequency can be verified */
CGM.OC_EN.B.EN = 1; /* Enable Output clock */
CGM.OCDS_SC.R = 0x23000000; /* And select output as system clock / 4 */
SIU.PCR[0].R = 0x0A04; /* PA0 ALT2 function (Clkout), MAX SRC */
}

/***** void Environment_Init(void) *****/
//! This function initialize the device
/*!
Called functions:
- SWT_Disable();
- MODE_Init();
- PLL_Init();
- asm_init_cache();

\brief This function configure the PLL
\return No return value.
\retval void

\note Start also the core 1
Set clock source as PLL, change mode and check clock is PLL
*/
void Environment_Init(void){
    SWT_Disable(); /* Disable Software Watchdog Timer (Can also be disabled in Shadow
row) */

    MODE_Init(); /* Configure modes and activate all clocks for all peripherals */

    CGM.Z0_DCR.B.DIV = 0x1; /* Z0 clock divider to divide by 2 */
    CGM.Flash_DCR.B.DIV = 0x1; /* Flash register interface /2 (default) */

    PLL_Init(); /* Set system clock to 120MHz based on 40Mhz XTAL */

    asm_init_cache(); /* Enable Cache 4WAY */

    /* Start Z0 Core */
    SSCM.DPMBOOT.R = 0x00180000; /* Start address of Z0 (2nd Flash block) */
    SSCM.DPMKEY.R = 0x00005AF0; /* Write key 1 */
    SSCM.DPMKEY.R = 0x0000A50F; /* Write key 2 */

}
/*****

```

```

| function implementations (scope: module-exported)
|-----*/
/***** int main(int argc, char *argv[]) *****/
//! This is the main function
/*!
    Called functions:
    - Environment_Init()

\param[in] argc (argument) see type definition
\param[in] *argv[] (list) type definition
\brief This code is a blink led example
\return function result.
\retval integer

\note
*/
int main(int argc, char *argv[]){

    Environment_Init();/* Basic device Initilaizations (Modes,Pll,Start core 1,...)
*/

    /* Example Code start here */
    /* Loop forever Flashing an LED connected to Port PE[4] (core Z0 code blink
contiguous led) */
    SIU.PCR[PIN_NUMBER].R = 0x0200; /* PE[4] to GPIO mode, output */

    while(1){
        SIU.GPDO[PIN_NUMBER].R = ~(SIU.GPDO[PIN_NUMBER].R) & 0x01; /* Invert LED
output */
        for (count=0; count<1000000; count++); /* wait a while */
    };
    return 0;
} /* End Of Main */

#ifdef __cplusplus
}
#endif

```

A.2 crt0_corez4_Flash.s

```

#/******
#/* DESCRIPTION:
#/* This is the initialization (crt0) file for SPC5646X devices running*/
#/* from Flash in VLE mode
#/*
#/* CONFIGURATIONS:
#/* (1) Configures the Reset Config Half word for VLE */
#/* (2) Configures MMU TLB entry 1 for 128KB RAM at 0x4000_0000 */
#/* (3) Configures peripherals space (IPBridge) on MMU TLB entry 2 */
#/* (4) Initialises the ECC in the SRAM by writing all words */
#/* (5) Copies Flash MMU (MMU TLB entry 0) Code and Flash Wait states */
#/* reduction code to RAM, runs it and return back to Flash */
#/* (6) Configure wait states for SRAM and Flash */
#/* (7) Configure Crossbar (XBAR)*/
#/* (8) Enable SPE
#/* (9) Enable BTB
#/*
#/* This code contains also a function to enable */
#/* the Instruction Cache in 4WAY configuration*/
#/*
#/* MMU configuration is:
#/* 0 - 0x0000_0000 to 0x00FF_FFFF (16MB VLE) Flash */
#/* 1 - 0x4000_0000 to 0x4001_FFFF (128KB VLE) RAM */
#/* 2 - 0xC000_0000 to 0xFFFF_FFFF (1GB VLE) Platform Peripherals */
#/*
#/******
#/* RCHW Configuration (and referencing of start label for linker) */
#/******
.section .rchw
.LONG 0x015A0000 #/* RCHW: VLE bit, Valid Boood Identifier 0x5A */
.LONG _start
.file "crt0_corez4_Flash.s"

.section .vletext_boot, "vax"
.vle

#.global _start
.global __ghs_board_memory_init
.global asm_init_cache

.equ MPR0ADDR, 0xFFFF0400
.equ MPR0VALUE, 0x76543210#/* Flash PORT1: Priority to corez4(instruct.)*/*
.equ SGPCR0VALUE, 0x0
.equ MPR1ADDR, 0xFFFF0410
.equ MPR1VALUE, 0x76543201#/* Flash PORT1: Priority to corez4(data)*/*
.equ SGPCR1VALUE, 0x1
.equ MPR2ADDR, 0xFFFF0420
.equ MPR2VALUE, 0x54376201#/* PRAM0: Priority to corez4(data)*/*
.equ SGPCR2VALUE, 0x1
.equ MPR3ADDR, 0xFFFF0430
.equ MPR3VALUE, 0x54301276#/* PRAM1: Priority to corez0(data)*/*
.equ SGPCR3VALUE, 0x4
.equ MPR7ADDR, 0xFFFF0470
.equ MPR7VALUE, 0x54327106#/* PBRIDGE: Priority to corez4(data)*/*
.equ SGPCR7VALUE, 0x1

#/*_start: */#/* uncomment this line and comment the following one */
#/* you don't use GHS libraries (take care to configure
SDA/Stack/..pointers */

```

```

__ghs_board_memory_init:

#/******
#/* MMU configuration code for SRAM */
#/* TLB1, Entry 1 128KB 0x4000_0000 to 0x4001_FFFF */
#/******
    e_lis r3, 0x1001
    mtmas0 r3      /* MAS0 */

    e_lis r3, 0xC000
    e_or2i r3, 0x0380
    mtmas1 r3      /* MAS1 = 0xC0000380 (128Kb) */

    e_lis r3, 0x4000
    e_or2i r3, 0x0028
    mtmas2 r3      /* MAS2 = 0x40000028 */

    e_lis r3, 0x4000
    e_or2i r3, 0x003F
    mtmas3 r3      /* MAS3 = 0x4000003F */

    tlbwe          /* Write the entry to the TLB */

#/******
#/* MMU configuration code for Peripheral Area (IPBridge) */
#/* TLB1, entry 2 1GB 0xC000_0000 to 0xFFFF_FFFF */
#/******
    e_lis r3, 0x1002 /* MAS0, Configure TLB1, Entry 2 */
    mtmas0 r3
    e_lis r3, 0xC000 /* MAS1 = 0xC0000A00 */
    e_or2i r3, 0x0A00
    mtmas1 r3
    e_lis r3, 0xC000 /* MAS2 = 0xC000002A */
    e_or2i r3, 0x002A
    mtmas2 r3
    e_lis r3, 0xC000 /* MAS3 = 0xC000003F */
    e_or2i r3, 0x003F
    mtmas3 r3

    tlbwe          /* Write the entry to the TLB */

#/******
#/* Initialize all SRAM space by copying all 32GPR's to RAM (fast) */
#/* Counter defines number of 32 x 32-bit words needed to write to RAM */
#/******
    e_lis r5, _SRAM_ADDR_Z4@h /* SRAM start address defined in the linker file */
    e_or2i r5, _SRAM_ADDR_Z4@l

    e_lis r6, _SRAM_SIZE_Z4@h /* SRAM size defined in the linker file */
    e_or2i r6, _SRAM_SIZE_Z4@l

    e_srwi r6, r6, 0x7 /* Divide SRAM size by 128 bytes */
    mtctr r6 /* Move to counter for use with "bdnz" */

sram_loop:
    e_stmw r0,0x0(r5) /* Write all 32 registers to SRAM */
    e_addi r5,r5,128 /* Increment the RAM pointer to next */
    /* 128byte(4bytes*32 registers) */
    e_bdnz sram_loop /* Loop for all of SRAM */

#/******
#/* Flash Wait States and MMU configurations code will be copied to SRAM*/
#/* to avoid inconsistencies */

```

```

#/******
e_b conf_sram#/* Copy code between conf_sram_code_begin and conf_sram_code_end to
SRAM */

conf_sram_code_begin:#/* ---- Start of block that will be copied to RAM */

#/******
#/* Configure the Flash wait states and the prefetch buffers -> copy to RAM*/
#/* Code is copied to RAM first, then executed, to avoid executing code */
#/* from Flash while wait states are changing. */
#/******
#/* PFCR0 = 0x294BFDFD (settings for 120MHz) */
#/* APC and RWSC = 0b101 (5 additional hold cycles) */
#/* WWSC = 0b101 (5 wait) */
#/* B02_P0_DPFE = 0b1 (enabled) */
#/* B02_P0_IPFE = 0b1 (enabled) */
#/* B02_P0_PFLIM = 0b1x (prefetch on miss or hit) */
#/* B02_P0_BFE = 0b1 (enabled) */ sla

e_lis r3, 0x294B
e_or2i r3,0xFDFD #/* NOTE: 0xaDaD = 0xaFaF */

e_lis r4, 0xC3F8 #/* PFCR0 ADDRESS HIGH */
e_or2i r4, 0x801C#/* PFCR0 ADDRESS LOW */
e_stw r3, 0(r4)
se_isync
msync

#/* PFAPR = 0x0300FFFF
e_lis r3, 0xFF00#/* Round-robin arbitration-Prefetching enabled. */
e_or2i r3, 0xFFFF#/* Both read and write accesses */
e_lis r4, 0xC3F8#/* PFAPR ADDRESS HIGH */
e_or2i r4, 0x8024#/* PFAPR ADDRESS LOW */
e_stw r3, 0(r4)
se_isync
msync

#/******
#/* MMU configuration code for Flash (TLB1 entry 0) -> copy to RAM */
#/* TLB1 entry 0, 0x0000_0000 to 0x00FF_FFFF overwriting existing TLB */
#/* infact MMU have configured the small 4 KB block at the reset vector. */
#/* NOTE: this configuration allows access to all device Flash */
#/******
#/* ---- MMU configuration (TLB1, Entry 0) for Code Flash:this block will be copied
to RAM */
e_lis r3, 0x1000 #/* MAS0, Configure TLB1, Entry 0 */
mtmas0 r3
e_lis r3, 0xC000 #/* MAS1 = 0xC0000700 (16MB) */
e_or2i r3, 0x0700
mtmas1 r3
e_lis r3, 0x0000 #/* MAS2 = 0x00000020 */
e_or2i r3, 0x0020
mtmas2 r3
e_lis r3, 0x0000 #/* MAS3 = 0x0000003F */
e_or2i r3, 0x003F
mtmas3 r3
tlbwe #/* Write the entry to the TLB */

#/* Configuration done...Jump to Flash again */
e_lis r24, run_from_Flash@h
e_or2i r24, run_from_Flash@l
se_mtctr r24

```




```

    se_bctr      /* Return to Flash (when running from RAM) */

conf_sram_code_end:/* ---- End of block that will be copied to RAM */

conf_sram:
/* Calculate number of bytes to copy (data between labels) */
    e_lis r3, conf_sram_code_begin@h
    e_or2i r3, conf_sram_code_begin@l
    e_lis r4, conf_sram_code_end@h
    e_or2i r4, conf_sram_code_end@l
    subf r4, r3, r4
    mtctr r4      /* Move to counter register the number of bytes to copy */

    e_lis r5, _SRAM_ADDR_Z4@h /* SRAM start address defined in the linker file */
    e_or2i r5, _SRAM_ADDR_Z4@l

copy_configuration_code:/* Copy configuration code from Flash to RAM */
    e_lbz r6, 0(r3)
    e_stb r6, 0(r5)
    e_addi r3, r3, 1
    e_addi r5, r5, 1
    e_bdnz copy_configuration_code/* Loop is based on the value of counter */

    e_lis r24, _SRAM_ADDR_Z4@h /* SRAM start address defined in the linker file */
    e_or2i r24, _SRAM_ADDR_Z4@l

    se_mtctr r24
    se_bctr      /* Jump to the SRAM Start address */

run_from_Flash:
#/*-----*/
/* Configure SRAM wait states to 1 */
/* RAM needs an additional wait state if the system clock is above 64 Mhz */
#/*-----*/
    e_lis r3, 0x4000/* 1-wait state for RAM access */
    e_or2i r3, 0x0

    e_lis r4, 0xFFFF/* ECSM */
    e_or2i r4, 0x0024
    e_stw r3, 0(r4)
    se_isync
    msync

#/*-----*/
/* Configure XBAR */
#/*-----*/
/* Configure Master Priority Register 0 */
    e_lis r4, MPROVALUE@h/* MPR0 Conf. High Value */
    e_or2i r4, MPROVALUE@l /* MPR0 Conf. Low Value */

    e_lis r5, MPROADDR@h/* MPR0 Address High Value */
    e_or2i r5, MPROADDR@l/* MPR0 Address Low Value */
    se_stw r4,0x0(r5) /* Store Value */

/* Configure Slave General Purpose Control Register 0 */
    e_lis r4, SGPCR0VALUE@h/* SGPCR0 High Value High Value */
    e_or2i r4, SGPCR0VALUE@l /* SGPCR0 Low Value */

    se_stw r4,0x10(r5) /* Store Value (SGPCR0 address is 0x10 bytes after MPR0)*/

/* Configure Master Priority Register 1 */

```

```

e_lis r4, MPR1VALUE@h#/* MPR1 Conf. High Value */
e_or2i r4, MPR1VALUE@l #/* MPR1 Conf. Low Value */

e_lis r5, MPR1ADDR@h#/* MPR1 Address High Value */
e_or2i r5, MPR1ADDR@l#/* MPR1 Address Low Value */
se_stw r4,0x0(r5) #/* Store Value */

/* Configure Slave General Purpose Control Register 1 */
e_lis r4, SGPCR1VALUE@h#/* SGPCR1 High Value High Value */
e_or2i r4, SGPCR1VALUE@l #/* SGPCR1 Low Value */

se_stw r4,0x10(r5) #/* Store Value (SGPCR1 address is 0x10 bytes after MPR1)*/

/* Configure Master Priority Register 2 */
e_lis r4, MPR2VALUE@h#/* MPR2 Conf. High Value */
e_or2i r4, MPR2VALUE@l #/* MPR2 Conf. Low Value */

e_lis r5, MPR2ADDR@h#/* MPR2 Address High Value */
e_or2i r5, MPR2ADDR@l#/* MPR2 Address Low Value */
se_stw r4,0x0(r5) #/* Store Value */

/* Configure Slave General Purpose Control Register 2 */
e_lis r4, SGPCR2VALUE@h#/* SGPCR2 High Value High Value */
e_or2i r4, SGPCR2VALUE@l #/* SGPCR2 Low Value */

se_stw r4,0x10(r5) #/* Store Value (SGPCR2 address is 0x10 bytes after MPR2)*/

/* Configure Master Priority Register 3 */
e_lis r4, MPR3VALUE@h#/* MPR3 Conf. High Value */
e_or2i r4, MPR3VALUE@l #/* MPR3 Conf. Low Value */

e_lis r5, MPR3ADDR@h#/* MPR3 Address High Value */
e_or2i r5, MPR3ADDR@l#/* MPR3 Address Low Value */
se_stw r4,0x0(r5) #/* Store Value */

/* Configure Slave General Purpose Control Register 3 */
e_lis r4, SGPCR3VALUE@h#/* SGPCR3 High Value High Value */
e_or2i r4, SGPCR3VALUE@l #/* SGPCR3 Low Value */

se_stw r4,0x10(r5) #/* Store Value (SGPCR3 address is 0x10 bytes after MPR3)*/

/* Configure Master Priority Register 7 */
e_lis r4, MPR7VALUE@h#/* MPR3 Conf. High Value */
e_or2i r4, MPR7VALUE@l #/* MPR3 Conf. Low Value */

e_lis r5, MPR7ADDR@h#/* MPR7 Address High Value */
e_or2i r5, MPR7ADDR@l#/* MPR7 Address Low Value */
se_stw r4,0x0(r5) #/* Store Value */

/* Configure Slave General Purpose Control Register 3 */
e_lis r4, SGPCR7VALUE@h#/* SGPCR7 High Value High Value */
e_or2i r4, SGPCR7VALUE@l #/* SGPCR7 Low Value */

se_stw r4,0x10(r5) #/* Store Value (SGPCR7 address is 0x10 bytes after MPR7)*/

#/******
#/* Enable Signal Processing extension (SPE) in Machine State Register */
#/******
mfMSR r3
e_or2is r3, 0x0200
mtMSR r3
#/******
#/* Enable Branch Target Buffers BTB */

```

```

#/******
e_lir0, 0x201
mfspr1013, r0

se_blr          /* Jump to Caller */

#e_bl main /* Use this Branch and comment the previous if you not use GHS
crt0.ppc */

.type __ghs_board_memory_init,@function
.size __ghs_board_memory_init,$-__ghs_board_memory_init

##-----

#*****
# invalidate and enable the instruction cache (4WAY)
#*****
asm_init_cache:
    e_lis r3, 0x0
    e_or2i r3,0x0002
    mtl1csr1 r3

loop_invalid_cache:
    msync
    mfl1csr1 r3
    e_and2i.r3,2
    se_bne loop_invalid_cache

# inst cache enable (4way)
    e_lis r3, 0x0
    e_or2i r3, 0x0011#(use 0x0001 for 2way)
    mtl1csr1 r3

se_blr

```

Appendix B Linker file

The linker files for the two projects are quite similar but of course the code Flash and the SRAM memory space are located at different addresses for the two cores.

[Table 4](#) shows the memory partitioning between the two cores:

Table 4. Memory partition schema

Memory area	Memory range	Size
e200z4d code Flash	0x0000_0000 - 0x0017_FFFF	1.5M
e200z4d SRAM	0x4000_0000 - 0x4001_FFFF	128K
e200z0h code Flash	0x0018_0000 - 0x002F_FFFF	1.5M
e200z0h SRAM	0x4002_0000 - 0x4003_FFFF	128K

As discussed previously the e200z0h linker file doesn't provide any RCHW section because the core is started by the e200z4d.

Below is showed the GHS (GreenHills) linker file for e200z4d core:

```

DEFAULTS {
    Flash_SIZE = 3M /* 3M Internal Flash */
    Flash_ADDR= 0x0

    Flash_SIZE_Z4 = 1536K /* 1.5M Internal Flash for Z4 Core */
    Flash_ADDR_Z4= 0x0
    Flash_SIZE_Z0 = 1536K/* 1.5M Internal Flash for Z0 Core */
    Flash_ADDR_Z0= 0x00180000

    SRAM_SIZE = 256K /* 256K od SRAM */
    SRAM_ADDR = 0x40000000

    SRAM_SIZE_Z4 = 128K /* 128K od SRAM for Z4 Core */
    SRAM_ADDR_Z4= 0x40000000
    SRAM_SIZE_Z0 = 128K /* 128K od SRAM for Z0 Core */
    SRAM_ADDR_Z0 = 0x40020000

    stack_size = 16k
    heap_size = 32k
}

MEMORY {

// 3M Internal Flash
    Flash_rsvd1: ORIGIN = 0x00000000, LENGTH = 0x10
    Flash_memory_z4:ORIGIN = ., LENGTH = Flash_SIZE_Z4-0x10
    Flash_memory_z0:ORIGIN = ., LENGTH = Flash_SIZE_Z0
    Flash_rsvd2: ORIGIN = ., LENGTH = 0

// 128KB of internal SRAM starting at 0x40000000
    sram_rsvd1: ORIGIN = 0x40000000,LENGTH = 0
    sram_reset: ORIGIN = ., LENGTH = 0
    sram_memory_z4: ORIGIN = ., LENGTH = SRAM_SIZE_Z4
    sram_memory_z0: ORIGIN = SRAM_ADDR_Z0, LENGTH = SRAM_SIZE_Z0
    sram_rsvd2: ORIGIN = ., LENGTH = 0
    
```

```

}

//
// Program layout for starting in ROM, copying data to RAM,
// and continuing to execute out of ROM.
//
SECTIONS
{
    .rchw          : > Flash_rsvd1

//
// ROM SECTIONS
//
.vletext_boot: {} > Flash_memory_z4 /* VLE Code */
.text          : > .
.vletext: > .
.fixaddr       : {} > . /* Required for          */
.fixtype       : {} > . /* compatibility with */
.secinfo       : {} > . /* GHS provided startup */
.syscall       : {} > /* code */

.rodata : {*(.rdata) *(.rodata)} > . /* Read Only Data */

.ROM.dataROM(.data) : {} > . /* Store Initialised RAM Variables */
.ROM.sdata ROM(.sdata) : {} > . /* temporarily in Flash */
.ROM.sdata2ROM(.sdata2): {} > . /* temporarily in Flash */

.xcptn ALIGN(0x10000) : {} > . /* Exception Vector Table (IVPR) - align 64K
boundary */
.isrvectbl ALIGN(0x800) : {} > . /* ISR Vector Table - must be 2K aligned */

//
// RAM SECTIONS
//
.data          : {} > sram_memory_z4 /* Initialised Data */
.bss           : {} > . /* Uninitialised Data */

.sdatabase ALIGN(16): {} > /* Base location for SDA Area */
.sdata         : {} > . /* Small Initialised Data (Area1) */
.sbss          : {} > . /* Small Uninitialised Data (Area1) */
.sdata2        : {} > . /* Small Initialised Constant Data */
.sbss2         : {} > . /* Small Uninitialised Data (Area2) */

.heap ALIGN(16) PAD(heap_size) : > .
.stack ALIGN(16) PAD(stack_size) : > .

_SRAM_SIZE= SRAM_SIZE;// Labels Used for Initialising SRAM ECC
_SRAM_ADDR= SRAM_ADDR;// Labels Used for Initialising SRAM ECC

_SRAM_SIZE_Z4= SRAM_SIZE_Z4;// Labels Used for Initialising SRAM ECC
_SRAM_ADDR_Z4= SRAM_ADDR_Z4;// Labels Used for Initialising SRAM ECC
_SRAM_SIZE_Z0= SRAM_SIZE_Z0;// Labels Used for Initialising SRAM ECC
_SRAM_ADDR_Z0= SRAM_ADDR_Z0;// Labels Used for Initialising SRAM ECC

//
// These special symbols mark the bounds of RAM and ROM memory.
// They are used by the MULTI debugger.
//
__ghs_ramstart = MEMADDR(sram_rsvd1);
__ghs_ramend   = MEMENDADDR(sram_memory_z4);
__ghs_romstart = MEMADDR(Flash_rsvd1);

```

```
__ghs_romend    = MEMENDADDR(Flash_rsvd2);  
//  
// These special symbols mark the bounds of RAM and ROM images of boot code.  
// They are used by the GHS startup code (_start and __ghs_ind crt0).  
//  
__ghs_rambootcodestart = 0;  
__ghs_rambootcodeend   = 0;  
__ghs_rombootcodestart = MEMADDR(Flash_memory_z4);  
__ghs_rombootcodeend   = MEMENDADDR(Flash_memory_z4);  
}
```

Appendix C Further information

C.1 Reference document

1. *SPC564Bxx, SPC56ECxx 32-bit MCU family built on the Power Architecture® for automotive body electronics applications (SPC564Bxx, SPC56ECxx datasheet, Doc ID 17478)*
2. *SPC564Bxx, SPC56ECxx 32-bit MCU family built on the embedded Power Architecture® (SPC564Bxx, SPC56ECxx RM0070 Doc ID 18196)*

C.2 Acronyms and abbreviations

A short list of acronyms and abbreviations used in this document is reported in ([Section C.1: Reference document](#)) for completeness.

Table 5. Acronyms and abbreviations

Terms	Meanings
BAM	Boot assist module
CR	Control register
DMA	Direct memory access
ECC	Error correcting code
GPIO	General purpose input/output
MC_CGM	Clock generation module
MC_ME	Mode entry
MCM	Miscellaneous control module
MMU	Memory management unit
MPU	Memory protection unit
NVM	Not-volatile memory
PLL	Phase locked loop
SoC	System on chip
SoR	Sphere of replication
SSCM	System status and configuration module
ST	STMicroelectronics
SWT	Software watchdog timer
TLB	Translation lookaside buffer

Revision history

Table 6. Document revision history

Date	Revision	Changes
10-Nov-2011	1	Initial release.
17-Sep-2013	2	Updated disclaimer.

Please Read Carefully:

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

ST PRODUCTS ARE NOT DESIGNED OR AUTHORIZED FOR USE IN: (A) SAFETY CRITICAL APPLICATIONS SUCH AS LIFE SUPPORTING, ACTIVE IMPLANTED DEVICES OR SYSTEMS WITH PRODUCT FUNCTIONAL SAFETY REQUIREMENTS; (B) AERONAUTIC APPLICATIONS; (C) AUTOMOTIVE APPLICATIONS OR ENVIRONMENTS, AND/OR (D) AEROSPACE APPLICATIONS OR ENVIRONMENTS. WHERE ST PRODUCTS ARE NOT DESIGNED FOR SUCH USE, THE PURCHASER SHALL USE PRODUCTS AT PURCHASER'S SOLE RISK, EVEN IF ST HAS BEEN INFORMED IN WRITING OF SUCH USAGE, UNLESS A PRODUCT IS EXPRESSLY DESIGNATED BY ST AS BEING INTENDED FOR "AUTOMOTIVE, AUTOMOTIVE SAFETY OR MEDICAL" INDUSTRY DOMAINS ACCORDING TO ST PRODUCT DESIGN SPECIFICATIONS. PRODUCTS FORMALLY ESCC, QML OR JAN QUALIFIED ARE DEEMED SUITABLE FOR USE IN AEROSPACE BY THE CORRESPONDING GOVERNMENTAL AGENCY.

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries.

Information in this document supersedes and replaces all information previously supplied.

The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners.

© 2013 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia - Malta - Morocco - Philippines - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

www.st.com